



Notes:

1. 5-Layer Flex, Material RF775
2. Min trace/space - 4 mils
3. 0.5 Oz copper on all layers
4. Silkscreen on Component side
5. Polyamide Coverlay (Kapton Soldermask) on top and bottom
6. Soft Au finish (ENIG) for Al wirebonding and hand soldering on all pads
7. Place stiffener on bottom side
8. Total thickness 0.012", not including stiffener

DAMIC - Die Test Flex - Rev.A
 SPC-3040 Mircea Bogdan
 10/13/2023 University of Chicago